## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of		Docket No.:				
Yo	oshitsugu MORITA et al.	71,051-039				
Serial No.:		Group Art Unit:				
10	0/584,655	unknown				
Filed:		Examiner:				
Ju	nne 26, 2006	unknown				
For:	Curing Silicone Composition and Cured Product Thereof	I hereby certify that the enclosed Information being transmitted via EFS transmiss Patents, PO BOX 1450, Alexandria, shown below.	ion to the Commissioner of			
		<u>07/06/07</u> Date	/Sandra Barry/ Sandra Barry			
P.O. E	Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450					
		LOSURE STATEMENT				
Dear S	ir:					
Applicant(s) submit(s) herewith patents, publications, or other information, of which they are aware that they believe may be material to the patentability and/or the examination of this application, and in respect of which, there may be a duty to disclose in accordance with 37 C.F.R. §1.56.						
The filing of this Information Disclosure Statement shall not be construed as a representation that a search has been made (37 C.F.R. 1.97(g) ), an admission that the information cited is, or is considered to be, material to patentability and/or examination, or that no other material information exists. The filing of this Information Disclosure Statement shall not be construed as an admission against interest in any manner.						
X Submitted herewith is Form PTO/SB/08a listing patents, publications, or other information for consideration by the Office.						
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X Legible copies of all items listed on Form PTO/SB/08a accompany this Information Disclosure Statement, except copies of U.S. patents, U.S. patent application publications, copies of U.S. applications that were filed on or after June 30, 2003, and copies of U.S. applications that were filed before June 30, 2003 that are available in the Image File Wrapper System.						
	Under 35 U.S.C. §120, this application relie No. [], filed on []. cited by the Office on this prior application application:	The following references were	submitted to and/or			

Information Disclosure Statement Page 2		
In accordance with 37 C.F.R. §1. this Information Disclosure State or publications listed on Form PT	ment, and is cumulative o	
FOREIGN LANGUAGE DOCUMENTS		
There are no foreign language do	ocuments listed on Form I	PTO/SB/08a.
X English language abstract for the	following non-English ref	erences are enclosed:
Foreign Patent Document  JP 3277619  JP 5295084  JP 7022441  JP 7118365  JP 7161740  JP 10130465  JP 10147764  JP 10163232  JP 60179417  JP 6306084	Publication Date 12/09/1991 11/09/1993 01/24/1995 05/09/1995 06/23/1995 05/19/1998 06/02/1998 06/19/1998 09/13/1985 11/01/1994	Name of Patentee or Applicant of Cited Document  Ito et al.  Morita et al.  Sakamoto et al.  Sakamoto et al.  Kobayashi et al.  Takeda et al.  Takeda et al.  Takeda et al.  Kondou Shiobara
Submitted herewith is an English publications or information or of to be material:		g foreign language patents, publications or information considered
X No English language translations parts thereof are readily available		patents, publications or information or above.
X The following foreign language d substantial equivalent of the Eng submitted herewith:		
<u>Cited Art</u> JP 3277619 JP 5295084 JP 60179417	US 5, EP 0	<b>Equivalent</b> 114,994 9567079 584,342
in the English language and indic	eating the degree of releva ne requirement (under 3	CT search report listing information not ancy found by the International Bureau 57 C.F.R. §1.98(a)(3)) for a concise
X A concise explanation of the rele included as presently understood knowledgeable about the content	by the individual designat	

Foreign Patent <u>Document</u>

**Explanation of Relevance** 

JP 7022441	The relevancy of this document as presently understood is obtained from the English language abstract which indicates that this document discloses a die bonding material made by reaction of a specific epoxy resin, containing a specified percentage of product wherein equivalent ratio between the epoxy resin and bisphenol group, with a curing agent and additives, such as inorganic filler.				
JP 7118365	The relevancy of this document as presently understood is obtained from the English language abstract which indicates that this document discloses a die bonding material obtained by mixing a reaction product of a specified epoxy resin with a phenol with an epoxy resin, a curing agent and an inorganic filler.				
JP 7161740	This document was cited by the International Searching Authority in the International Search Report as a Category "A" document and its relevance as presently understood is obtained from the English language abstract which indicates that this document a conductive resin paste for semiconductors composed of a specific epoxy resin, epoxy silane compounds, bisphenol, organic borate, and silver powder.				
JP 10130465	The relevancy of this document as presently understood is obtained from the English language abstract which indicates that this document discloses a die attaching paste made by blending an epoxy resin, a curing agent, a cyanic acid ester, and an inorganic filler with a product of the reaction of a bisphenol compound with a diglycidyl ether compound containing disiloxane.				
JP 10147764	The relevancy of this document as presently understood is obtained from the English language abstract which indicates that this document discloses a die attaching paste made by mixing an epoxy resin with a curing agent that is a specific reaction product of a cyanate resin and an epoxy dimethysiloxane compound, a cure accelerator, and an inorganic filler.				
JP10163232	The relevancy of this document as presently understood is obtained from the English language abstract which indicates that this document discloses a die attaching paste made by mixing a specific epoxy resin with a cyanate ester group.				
JP 6306084	The relevancy of this document as presently understood is obtained from the English language abstract which indicates that this document discloses an epoxy resin consisting of a specific epoxy-modified silicone and a specific modified silicone as a curing agent.				
A concise explanation of the relevance of the following listed non-English language information is set forth in the above-identified specification:					
<b>CERTIFICATION</b> :					
X The Information Disclosure Statement transmitted herewith is being filed <b>within</b> three (3) months of the filing date of the application or date of entry into the national stage of an international application or before the mailing date of a first Office Action on the merits, whichever event occurs last. 37 C.F.R. §1.97(b). Accordingly, it is believed that no certification or fee is due.					
The Information Disclosure Statement transmitted herewith is being filed <b>after</b> three (3) months of the filing date of the application or the date of entry into the national stage of an international application and after the mailing date of the first Office Action on the merits, but <b>before</b> the mailing date of either a final action under 37 C.F.R. §1.113 or a Notice of Allowance under 37 C.F.R. §1.311, whichever occurs first. Accordingly, I hereby certify that:					

Information Disclosure Statement Page 4
each item of information contained in the Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three (3) months prior to the filing of the Information Disclosure Statement; 37 C.F.R. §1.97(e)(1); <b>OR</b>
no item of information contained in the Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to my knowledge as the person signing this certification after making reasonable inquiry, no item of information contained in the Information Disclosure Statement was known to any individual designated in §1.56(c) more than three (3) months prior to the filing of this statement; 37 C.F.R. §1.97(e)(2); <b>OR</b>
Applicant elects the option to pay the fee set forth in 37 C.F.R. §1.17(p) for submission of an Information Disclosure Statement under 37 C.F.R. §1.97(c). If a check is not enclosed, please charge the \$180.00 IDS submission fee to Howard & Howard Attorneys PC Deposit Account No. 08-2789. A duplicate of this paper is enclosed.
The Information Disclosure Statement transmitted herewith is being filed <b>After a Final Action</b> under 37 C.F.R. §1.113, or <b>After a Notice of Allowance</b> under 37 C.F.R. §1.311, whichever occurs first, but is being filed on or <b>Before Payment of the Issue Fee</b> . Accordingly, I hereby certify that:
each item of information contained in the Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three (3) months prior to the filing of the statement; 37 C.F.R. §1.97(e)(1); <b>OR</b>
no item of information contained in the Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to my knowledge as the person signing this certification after making reasonable inquiry, no item of information contained in the Information Disclosure Statement was known to any individual designated in §1.56(c) more than three (3) months prior to the filing of this statement; 37 C.F.R. §1.97(e)(2); AND
Applicant hereby petitions for consideration of this Information Disclosure Statement; 37 C.F.R. §1.97(d)(2)(ii). If a check is not enclosed, please charge the petition fee of <b>\$180.00</b> Howard & Howard Attorneys PC <b>Deposit Account No. 08-2789</b> . A duplicate of this paper is enclosed.
The Commissioner is authorized to charge Howard & Howard Attorneys PC Deposit Account No. 08-2789 for any additional fees due hereunder.
Respectfully submitted

Reg. No.: 46,295

July 6, 2007

Date

/David M. LaPrairie/

David M. LaPrairie

Howard & Howard Attorneys PC The Pinehurst Office Center, Suite 101 39400 Woodward Avenue

Bloomfield Hills, MI 48304-5151

Tel. No.: (248) 723-0442

Customer No. 27305